



**Microelectronics Commons**  
**Call for Topics (CFT)**  
**Project No. 22-16-02**

<b>Project Title</b>	Microelectronics Commons
<b>Project Sponsor</b>	Office of the Under Secretary of Defense for Research and Engineering (OUSD R&E)
<b>Contracting Activity</b>	Naval Surface Warfare Center (NSWC), Crane Division
<b>Response Deadline</b>	24 July 2024 at 12:00 PM EST
<b>Authority</b>	Prototype Other Transaction Agreement (10 U.S.C. § 4022)

*All respondents must be active NSTXL members and Microelectronics Commons Hub Leads.*  
<https://microelectronicscommons.org/>

**1. Project Background/Objectives**

Microelectronics Commons is a CHIPS and Science Act-funded national network for onshore, microelectronics hardware focused prototyping, lab-to-fab transition of semiconductor technologies and semiconductor workforce training. In 2023, the Department of Defense (DoD) established the Microelectronics Commons – a network of eight regional hubs to evolve laboratory prototypes to fabrication prototypes (lab-to-fab) and to strengthen the semiconductor workforce. This Call for Topics (CFT) describes the desired technical ideas for which project proposals are being sought.

**2. Content of Topic Response:**

**a.** Responses must address the following:

1. Identify Teaming Partners (Lab-to-Fab) - Start-Ups, DIB Partners, COREs, etc.
2. Identify Transition Partners - Programs of Record, Commercial Transition Partners, DIB's, etc.
3. Any Attachments supporting the CFT response to include graphs and other pertinent information (Does not count towards page count).
4. Describe how Existing Hub Capabilities will accelerate Lab-to-Fab.
5. What Technical Area and how it ties to updated Technical Guidance.
6. Current State of the Technology and Desired End-State (Where is this topic going?).

- Is there a demonstrated prototype within the lab? If so, what's the current TRL/MRL?
  - Has this topic benefited from any previous investments (USG or IRAD)?
  - Does it add a new capability to the DIB or DoD at the system level?
  - Is there a proposed (or identified) transition opportunity or a commitment from a program of record or a DoD prime?
  - How does the proposed topic ensure long-term access (e.g. PDKs, IP, infrastructure, on-shoring of technology)?
  - Draft Success Criteria for a Topic (Metrics).
7. Fill out the Call for Topics (CFT) Summary Form (Attachment A) and include the full 3-5 page topic response within the same PDF as a cover sheet for the submitted topic. (Does not count towards page count).
  8. Fill out Call for Topics Summary Quad Chart (Does not count towards page count) (Attachment B).
  9. Fill out the Heilmeyer Response (Does not count towards page count) (Attachment C).

**b. General Response information:**

Responses are due no later than 12:00PM ET on **07/24/2024** and should be submitted via "[Submit a Topic](#)" button to the opportunity site at (<https://nstxl.org/opportunity/microelectronics-commons-call-for-topics>), select the "Current" tab, locate Microelectronics Commons.

Hub Leads may rank submissions by perceived priority.

The inclusion of classified material in the main body of the response is prohibited. The response is not required to contain classified material or information. If the respondent chooses to make classified material and information available, all classified material must be submitted in a separate Classified Appendix.

- General supporting classified information is limited to five (5) additional pages.
- The Classified Appendix must be classified no higher than collateral Top Secret//Sensitive Compartmented Information. The Classified Appendix can be submitted one of two methods:

For Collateral Secret

1) (Preferred) SIPRNet to: [timothy.morgan2@navy.smil.mil](mailto:timothy.morgan2@navy.smil.mil) or to

2) USPS mail Three (3) hardcopies of the Classified Appendix can be mailed via USPS to:

- Outside envelope:
  - Commander
  - Naval Surface Warfare Center
  - ATTN: Security Manager Bldg. 2
  - 300 Highway 361
  - Security Department
  - Crane, IN 47522-5001

- Inside envelope:
  - Commander
  - Naval Surface Warfare Center
  - ATTN: Tim Morgan
  - Bldg. 3334, Code GXDN
  - Crane, IN 47522-5001

For Top Secret and/or Sensitive Compartmented Information:

- 1) JWICS to: [timothy.a.morgan@coe.ic.gov](mailto:timothy.a.morgan@coe.ic.gov)

It is the respondent's responsibility to ensure the Classified Appendix is post-marked by the government prior to the submission deadline. The Classified Appendix must contain an additional cover page which includes the following:

- Company name
- Detailed Topic Title
- Commercial and Government Entity (CAGE) Code (if available)
- Level of facility clearance (if available)
- Street Address
- Primary and Secondary Point of Contact (with title, email address and phone number)
- Government Cognizant Security Office (CSO) responsible for monitoring the company's National Industrial Security Program Standards compliance (with address, email address and phone number)
- Company's security officer point of contact (with title, email address and phone number)
- All locations where work will be performed
- Business Size
- Business Type (Traditional or Non-Traditional)
- Status of U.S. ownership

In addition to Government evaluators, a contractor advisor will be providing support during source selection reviewing technical responses. The advisor(s) will be from the below organizations:

- Science Application International Corporation, 12010 Sunset Hills Rd, Reston, VA, 20190-5856, Cage Code 6XWA8
- Amentum Services, Inc., 4800 Westfields Blvd Suite 400, Chantilly, VA 20151-4247, Cage Code 5W3V7

If a respondent would like the contractor to sign a Non-Disclosure Agreement before having access to the response, attach a copy of the Non-Disclosure Agreement to the submission package.

There are no formatting restrictions (MS Word and/or Adobe PDF files preferred), however, responses should have a minimum of 3 pages and maximum of 5 pages with an Executive Summary on the CFT Summary Form with details within topic response.

The government reserves the right to use topic responses for FY25 and future Calls for Projects.